

Notification Number:	20200908002	Notification Date:	Jan. 11, 2021
Title:	Datasheet for TMS320F28004x		
Customer Contact:	Notification Manager	Dept:	Quality Services

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



[TMS320F280049](#), [TMS320F280049C](#)
[TMS320F280048](#), [TMS320F280048C](#), [TMS320F280045](#)
[TMS320F280041](#), [TMS320F280041C](#), [TMS320F280040](#), [TMS320F280040C](#)

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Changes from October 23, 2018 to April 29, 2020 (from D Revision (October 2018) to E Revision)	Page
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• Section 1.1 (Features): Changed "Ten hardware breakpoints" to "Ten hardware breakpoints (with ERAD)".	1
• Section 1.2 (Applications): Updated section.	2
• Figure 1-1 (Functional Block Diagram): Updated figure.	5
• Table 3-1 (Device Comparison): Changed ADC Conversion Time from 300 ns to 290 ns.	9
• Table 3-1 : Added number of CLB tiles.	9
• Table 3-1 : Added links to device numbers.	9
• Table 4-1 (Pin Attributes): Updated DESCRIPTION column of VDDIO_SW and VSS_SW.	16
• Table 4-4 (Power and Ground): Updated DESCRIPTION column of VDDIO_SW and VSS_SW.	29
• Table 4-10 (Connections for Unused Pins): Updated ACCEPTABLE PRACTICE column of GPIOx, VDDIO_SW, and VSS_SW.	52
• Section 5.1 (Absolute Maximum Ratings): Changed "Input clamp current" condition from "Digital input (per pin), ..." to "Digital/analog input (per pin), ...".	53
• Section 5.1 : Added footnote about continuous clamp current.	53
• Section 5.6 (Electrical Characteristics): Updated table.	53
• Section 5.2 (ESD Ratings – Commercial): Added ANSI/ESDA/JEDEC JS-002 to description of Charged-device model (CDM).	54
• Table 5-1 (System Current Consumption (External Supply)): Updated table. Updated/added footnotes.	56
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• Section 5.9.1.2 (Internal 1.2-V Switching Regulator (DC-DC)): Updated "The internal DC-DC regulator offers increased efficiency ..." paragraph.	65
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The datasheet number will be changing.

Device Family	Change From:	Change To:
TMS320F280049, TMS320F280049C TMS320F280048, TMS320F280048C, TMS320F280045, TMS320F280041, TMS320F280041C, TMS320F280040, TMS320F280040C	SPRS945D	SPRS945E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMS320F280049>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:			
None.			
Product Affected:			
F280040CPMQR	F280041PZQR	F280045PZSR	F280049CRSHSR
F280040PMQR	F280041PZS	F280045RSHSR	F280049PMS
F280041CPMS	F280041PZSR	F280048CPMQR	F280049PMSR
F280041CPZQR	F280041RSHSR	F280048PMQR	F280049PZQ
F280041CPZS	F280045PMS	F280049CPMS	F280049PZQR
F280041CRSHSR	F280045PMSR	F280049CPZQR	F280049PZS
F280041PMS	F280045PZS	F280049CPZS	SG00944PMS
F280041PMSR	F280049PZSR	F280049RSHSR	

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